1. Disassembly Procedures

- S1 Turn off the monitor.
- S2 Place the monitor on a soft cloth or cushion.

Press and hold the stand release button.

Lift the stand up and away from the monitor.



S3 Unlock 4 screws on Rear Cover

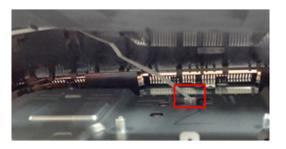


(Screw Torque: 9±1kgf)

S4 Disassemble Rear Cover from Middle Frame according to the sequence shown in the picture

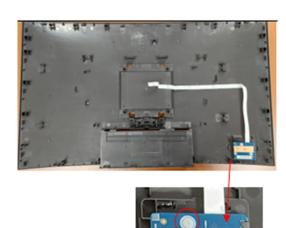


S5 Pull out CTRL BD FFC from I/F BD to take off Rear Cover



S6 Unlock 3 screws to disassemble CTRL BD from Rear Cover

Tear off CTRL BD FFC from Rear Cover and take off CTRL BD from Rear Cover



(Screw Torque: 2±0.5kgf)

S7 Disassemble CTRL BD FFC from CTRL BD



S8 Tear off a tape from Backlight Wire



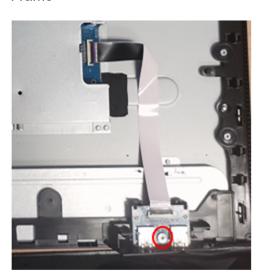
S9 Pull out Backlight wire from SPS BD



S10 Disassemble USB FFC from USB BD and I/F BD

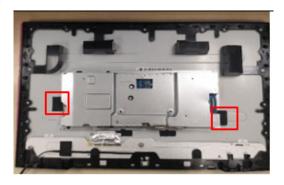
Unlock 1 screw on USB BD

Disassemble USB BD from Middle Frame



(Screw Torque: 4.5±0.5kgf)

S11 Tear of 2 tapes from Main SHD



S12 Tear off a aluminum foil from LVDS cable



S13 Tear off a yellow tape from LVDS cable



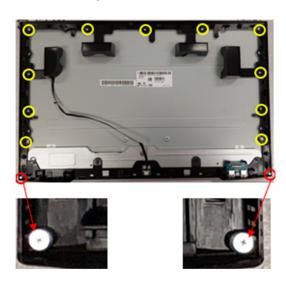
S14 Disassemble LVDS cable from Panel
Take off Main SHD from Panel



S15 Unlock 2 screws on "ASSY CHIN" (See Red mark)

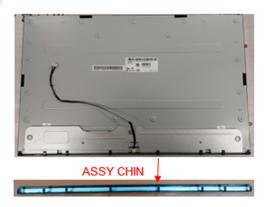
Unlock 11 screws on Middle Frame (See Yellow mark)

Disassemble Middle Frame from Panel and "ASSY CHIN"



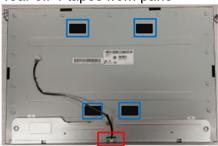
(Screw Torque_MF screw: 4.5±0.5kgf) (Screw Torque_"ASSY CHIN" screw: 2.0±0.1kgf)

S16 Disassemble "ASSY CHIN" from Panel



\$17 Pull out Backlight Wire from panel

Tear off 4 tapes from pane



\$18 Disassemble Mylar from Main SHD



S19 Unlock 4 hexagonal screws



(Screw Torque: 5.0±0.6kgf)

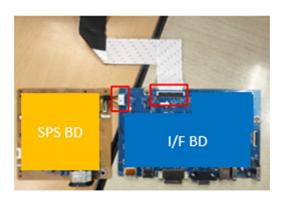
S20 Unlock 5 PCBA screws



(Screw Torque: 5.0±0.6kgf)

S21 Disassemble I/F BD and SPS BD from Main SHD

Pull out all wires on PCBA



Remove electrolyte capacitors (red mark) from printed circuit boards



S22

S22-1 Cut the glue between bulk cap. and PCB with a knife



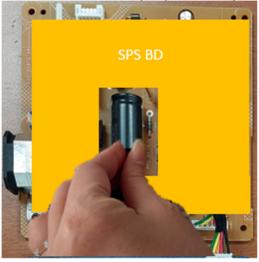
S22-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S22-3 Take out bulk cap. pin solder with soldering iron and absorber



S22-4 Lift the bulk cap. up and away from the PCB



2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

| Capacitors / condensers (containing PCB/PCT) | No used |
|--|--|
| Mercury containing components | No used |
| Batteries | No used |
| Printed circuit boards (with a surface greater | Product has printed circuit boards |
| than 10 square cm) | (with a surface greater than 10 square |
| | cm) |
| Component contain toner, ink and liquids | No used |
| Plastic containing BFR | No used |
| Component and waste contain asbestos | No used |
| CRT | No used |
| Component contain CFC, HCFC, HFC and | No used |
| HC | |
| Gas discharge lamps | No used |
| LCD display > 100 cm2 | Product has an LCD greater than 100 |
| | cm2 |
| External electric cable | Product has external cables |
| Component contain refractory ceramic fibers | No used |
| Component contain radio-active substances | No used |
| Electrolyte capacitors (height | Product has electrolyte capacitors |
| > 25mm, diameter > 25mm) | (height >25mm, diameter > 25mm) |

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber